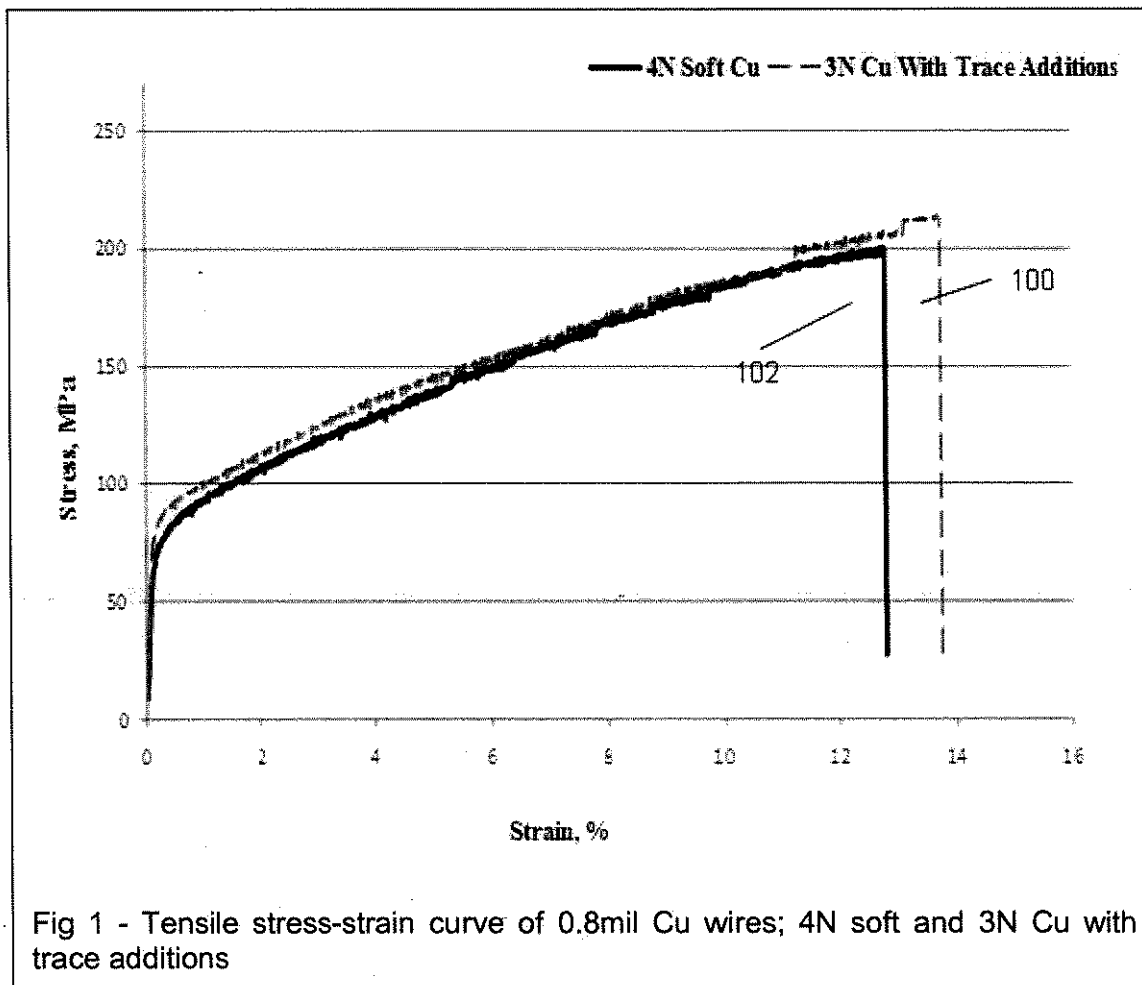




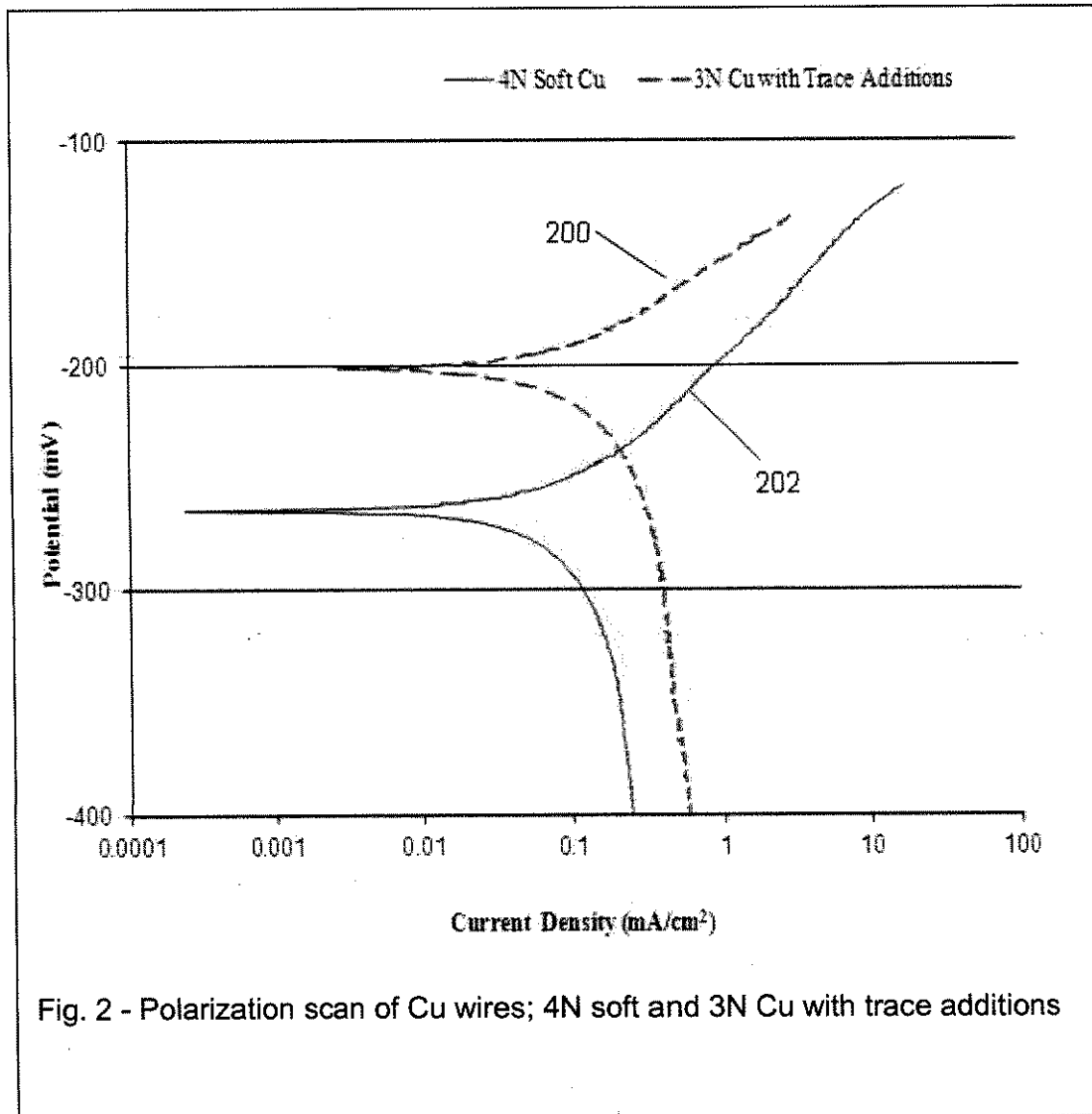




Fig 3 Ball bond of 3N Cu 0.8mil wire with trace additions

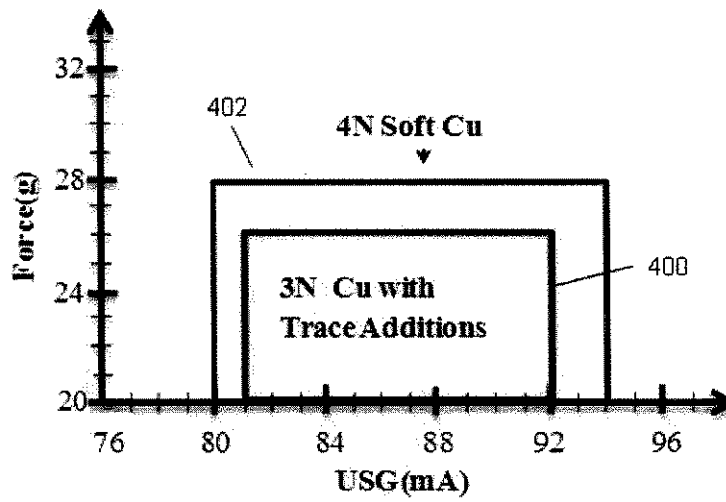


Fig 4(a) - Ball Bond Process Window

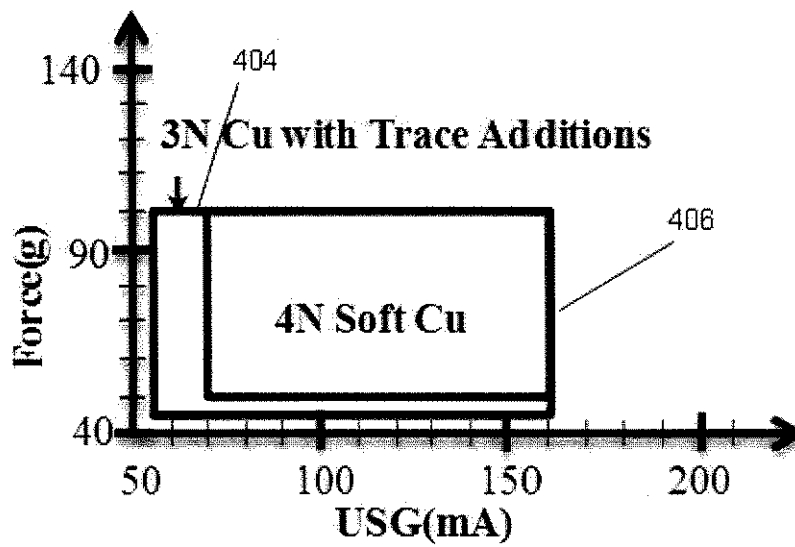


Fig 4(b) - Stitch Bond Process Window

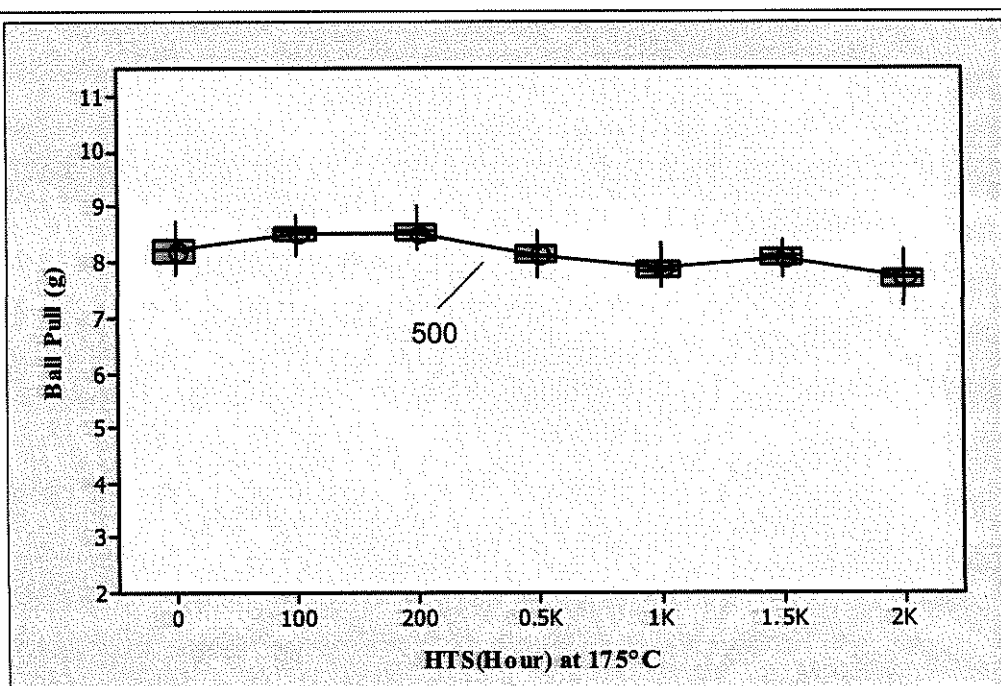


Fig 5(a) – Thermal aged 3N Cu 0.8mil wires with trace additions

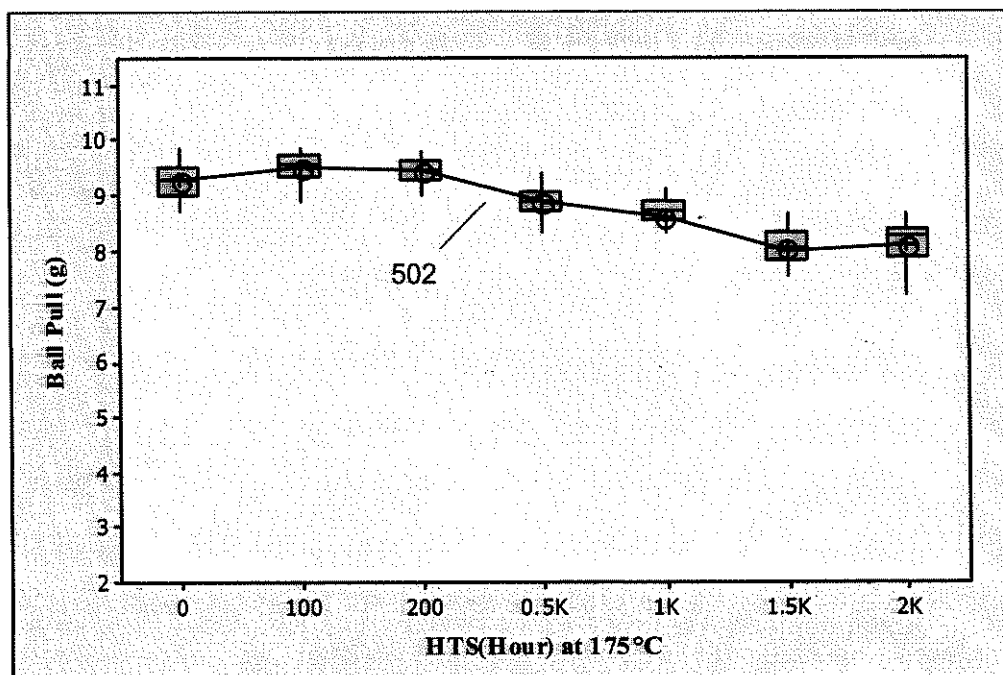


Fig 5(b) - Thermal aged 4N soft Cu 0.8mil wires